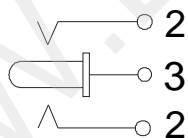
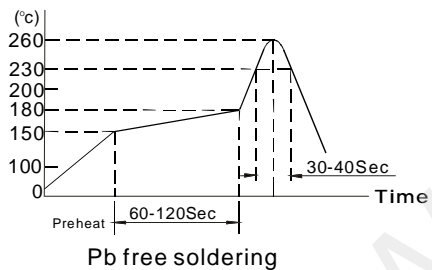
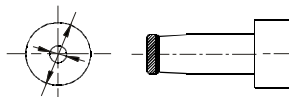


**SOLDERING CONDITIONS**



Circuit



Pad Layout



深圳市华宇创精密电子有限公司

<b>TOLERANCE:</b> X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	<b>DRAWN BY :</b> 陈一鸣	<b>DATE :</b> 2014-02-23	<b>PART NAME:</b> DC-058A
	<b>CHECKED BY:</b> 马跃	<b>DATE :</b> 2014-02-23	<b>PART NO.</b> HYC-DC058A-770 <b>MOLD NO.</b>
<b>UNIT:</b> mm [inch]	<b>APPROVED BY:</b> 邱国夷	<b>DATE :</b> 2014-02-23	<b>DRAW NO:</b> HYC-DC17031514 <b>SHEET NO.</b> 1 OF 1
<b>SCALE:</b> 1:1	<b>SIZE:</b> A4		